SOD323 SILICON HIGH CURRENT SCHOTTKY BARRIER DIODE "SuperBAT"

FEATURES

- Low V_F
- · High current capability
- Miniature surface mount package

APPLICATIONS

- DC DC converters
- Mobile telecomms
- PCMCIA

DEVICE MARKING

• Partmark detail - BD

SOD323



PINOUT - TOP VIEW



Partmark is for example only

ABSOLUTE MAXIMUM RATINGS

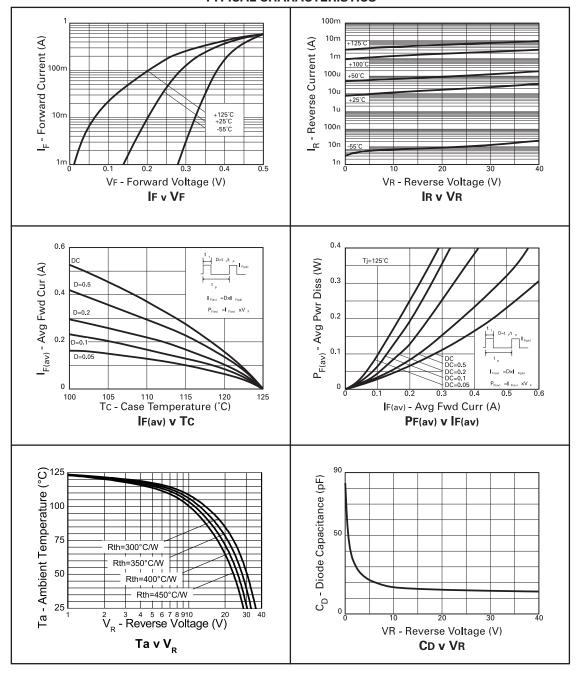
PARAMETER		SYMBOL	VALUE	UNIT
Continuous Reverse Voltage		V _R	40	V
Forward Current (Continuous)		I _F	400	mA
Forward Voltage @ I _F =400mA		V _F	500	mV
Average Peak Forward Current; D.C. = 5	0%	I _{FAV}	1000	mA
	t≤100μs t≤10ms	I _{FSM}	6.75 3	A A
Power Dissipation at T _{amb} =25°C		P _{tot}	250	mW
Storage Temperature Range		T _{stg}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse Breakdown Voltage	V _{(BR)R}	40	60		V	I _R =200μA
Forward Voltage	V _F		270 300 370 425 550 640 810 440	300 350 460 500 670 780 1050	mV mV mV mV mV mV	I _E =50mA I _F =100mA I _F =250mA I _F =400mA I _F =750mA I _F =1500mA I _F =500mA, T _{amb} =100°C
Reverse Current	IR		15	40	μΑ	V _R =30V
Diode Capacitance	C _D		20		pF	f=1MHz,V _R =25V



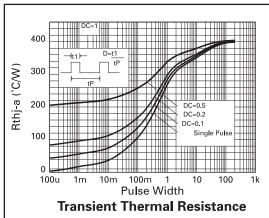
TYPICAL CHARACTERISTICS

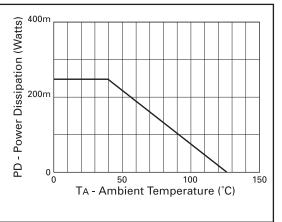




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TYPICAL CHARACTERISTICS (Cont.)







NOTES:



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- 1. are intended to implant into the body

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Product status key:

"Preview"Future device intended for production at some point. Samples may be available

"Active"Product status recommended for new designs

"Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect

"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

"Draft version"This term denotes a very early datasheet version and contains highly provisional

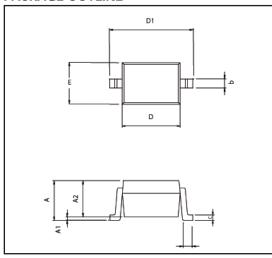
information, which may change in any manner without notice.

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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		DIM	Millimeters		
DIIVI	Min	Max	DIIVI	Min	Max	
Α	-	1.150	D	1.520	1.800	
A1	0.000	0.100	D1	2.300	2.700	
A2	0.800	-	Е	1.150	1.450	
b	0.250	0.400	L	0.100	0.400	
С	0.080	0.200	-	-	-	

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